NTMS4503N

Power MOSFET

28 V, 14 A, N−Channel, SOIC−8

Features

- Low $R_{DS(on)}$
- High Power and Current Handling Capability
- Low Gate Charge
- Pb−Free Package is Available

Applications

- DC/DC Converters
- Motor Drives
- Synchronous Rectifier − POL
- Buck Low−Side

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Drain−to−Source Voltage	V_{DSS}	28	V
Gate−to−Source Voltage − Continuous	V_{GS}	±20	V
Drain Current Continuous @ T_A = 25°C (Note 1) Continuous @ T_A = 25°C (Note 2) Continuous @ T_A = 25°C (Note 3) Single Pulse (tp = 10 μs)	I_D I_{DM}	 14 12 9.0 40	A
Total Power Dissipation T_A = 25°C (Note 1) T_A = 25°C (Note 2) T_A = 25°C (Note 3)	P_D	 2.5 1.66 0.93	W
Operating and Storage Temperature	T_J, T_{stg}	−55 to 150	°C
Single Pulse Drain−to−Source Avalanche Energy − Starting T_J = 25°C (V_{DD} = 30 V, V_{GS} = 10 V, I_L = 12.2 A, L = 1.0 mH, R_G = 25 Ω)	E_{AS}	75	mJ
Maximum Lead Temperature for Soldering Purposes, 1/8″ from case for 10 seconds	T_L	260	°C

THERMAL RESISTANCE RATINGS

Rating	Symbol	Value	Unit
Thermal Resistance Junction−to−Ambient (Note 1) Junction−to−Ambient (Note 2) Junction−to−Ambient (Note 3)	$R_{\theta JA}$	 50 75 135	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Surface−mounted on FR4 board using minimum recommended pad size (Cu area 0.412 in sq), t < 10 s.
2. Surface−mounted on FR4 board using 1″ pad size (Cu area 1.127 in sq) steady state.
3. Surface−mounted on FR4 board using minimum recommended pad size (Cu area 0.412 in sq), steady state.

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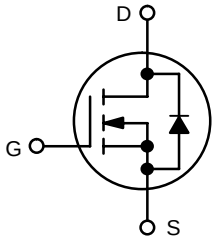
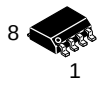
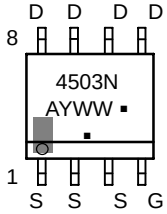
$V_{(BR)DSS}$	$R_{DS(on)}$ Typ	I_D Max (Note 1)
28 V	7.0 mΩ @ 10 V	14 A
	8.8 mΩ @ 4.5 V	



MARKING DIAGRAM & PIN ASSIGNMENT



SOIC−8
CASE 751
STYLE 12



4503N = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
NTMS4503NR2	SOIC−8	2500/Tape & Reel
NTMS4503NR2G	SOIC−8 (Pb−Free)	2500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Characteristic	Symbol	Test Condition		Min	Typ	Max	Unit
OFF CHARACTERISTICS							
Drain−to−Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0 V, I_D = 250 μA		28	31	−	V
Drain−to−Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$	−		−	22	−	mV/°C
Zero Gate Voltage Drain Current	I_{DSS}	V_{GS} = 0 V, V_{DS} = 24 V	T_J = 25°C	−	−	1.0	μA
			T_J = 100°C	−	−	25	
Gate−to−Source Leakage Current	I_{GSS}	V_{DS} = 0 V, V_{GS} = ±20 V		−	−	±100	nA
ON CHARACTERISTICS (Note 4)							
Gate Threshold Voltage	$V_{GS(TH)}$	V_{GS} = V_{DS}, I_D = 250 μA		1.0	−	2.0	V
Negative Threshold Temperature Coefficient	$V_{GS(TH)}/T_J$	−		−	−5.0	−	mV/°C
Drain−to−Source On Resistance	$R_{DS(on)}$	V_{GS} = 10 V, I_D = 14 A		−	7.0	8.0	mΩ
		V_{GS} = 4.5 V, I_D = 10 A		−	8.8	9.8	
Forward Transconductance	g_{FS}	V_{DS} = 10 V, I_D = 14 A		−	30	−	S
CHARGES, CAPACITANCES AND GATE RESISTANCE							
Input Capacitance	C_{ISS}	V_{GS} = 0 V, f = 1.0 MHz, V_{DS} = 16 V		−	2400	−	pF
Output Capacitance	C_{OSS}			−	1000	−	
Reverse Transfer Capacitance	C_{RSS}			−	375	−	
Total Gate Charge	$Q_{G(TOT)}$	V_{GS} = 4.5 V, V_{DS} = 16 V, I_D = 10 A		−	23	−	nC
Threshold Gate Charge	$Q_{G(TH)}$			−	2.0	−	
Gate−to−Source Charge	Q_{GS}			−	5.0	−	
Gate−to−Drain Charge	Q_{GD}			−	12	−	
SWITCHING CHARACTERISTICS, V_{GS} = V (Note 5)							
Turn−On Delay Time	$t_{d(ON)}$	V_{GS} = 4.5 V, V_{DD} = 16 V, I_D = 10 A, R_G = 2.0 Ω		−	18.5	−	ns
Rise Time	tr			−	70	−	
Turn−Off Delay Time	$t_{d(OFF)}$			−	21	−	
Fall Time	t_f			−	23	−	
DRAIN−SOURCE DIODE CHARACTERISTICS							
Forward Diode Voltage	V_{SD}	V_{GS} = 0 V, I_S = 10 A	T_J = 25°C	−	0.82	1.2	V
			T_J = 125°C	−	0.65	−	
Reverse Recovery Time	t_{RR}	V_{GS} = 0 V, d_{ISD}/d_t = 100 A/μs, I_S = 14 A		−	48	−	ns
Charge Time	T_a			−	23	−	
Discharge Time	T_b			−	25	−	
Reverse Recovery Charge	Q_{RR}			−	25	−	nC

4. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
5. Switching characteristics are independent of operating junction temperatures.

TYPICAL PERFORMANCE CURVES

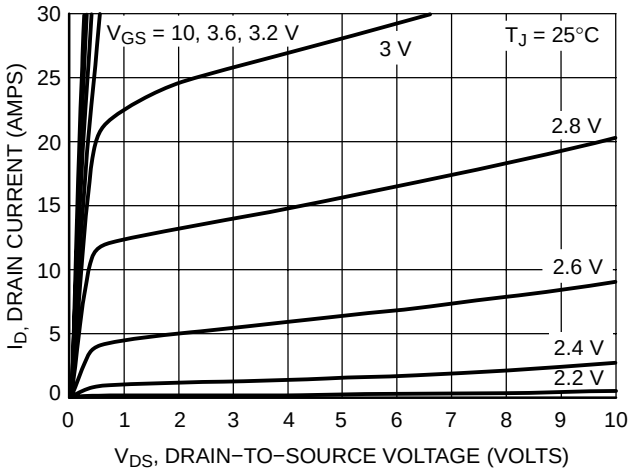


Figure 1. On−Region Characteristics

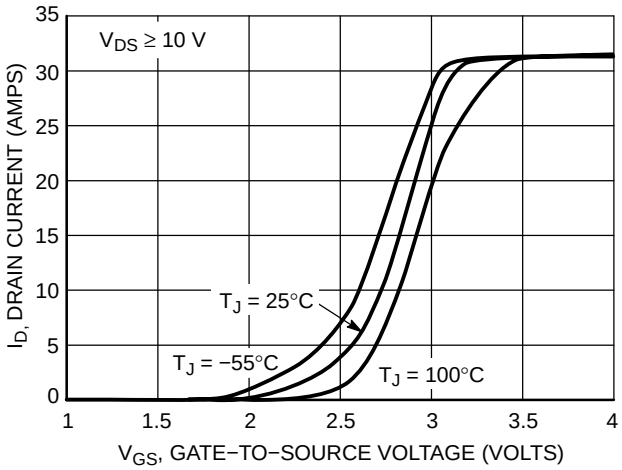


Figure 2. Transfer Characteristics

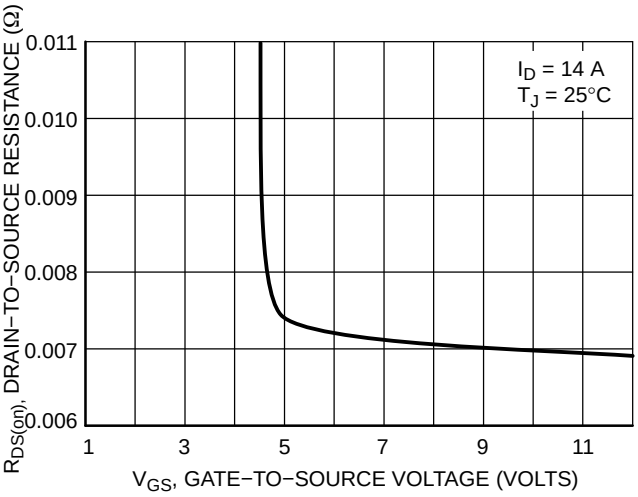


Figure 3. On−Resistance vs. Gate−to−Source Voltage

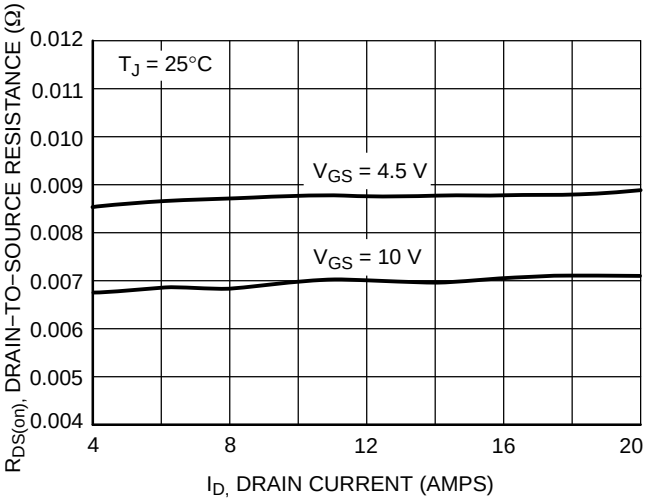


Figure 4. On−Resistance vs. Drain Current and Gate Voltage

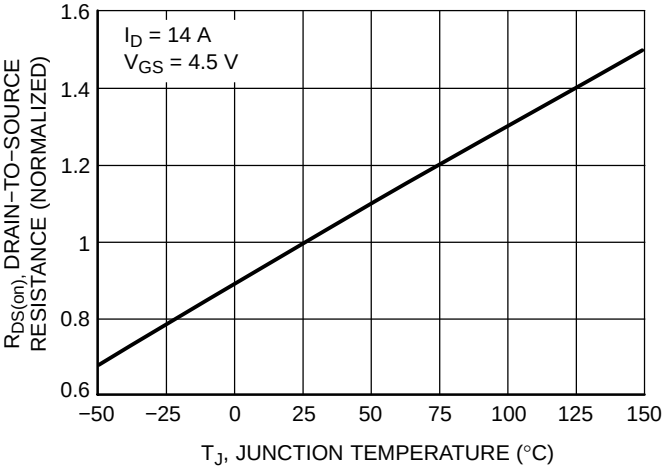


Figure 5. On−Resistance Variation with Temperature

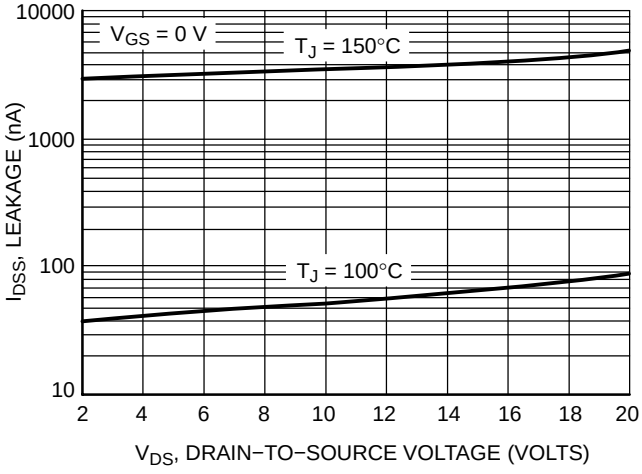


Figure 6. Drain−to−Source Leakage Current vs. Voltage

TYPICAL PERFORMANCE CURVES

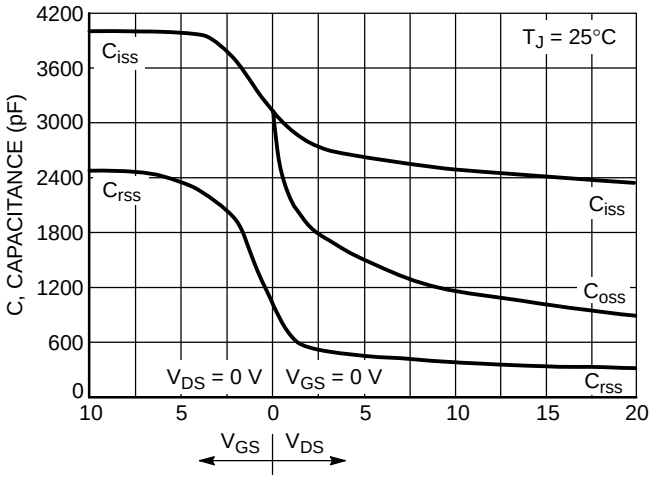


Figure 7. Capacitance Variation

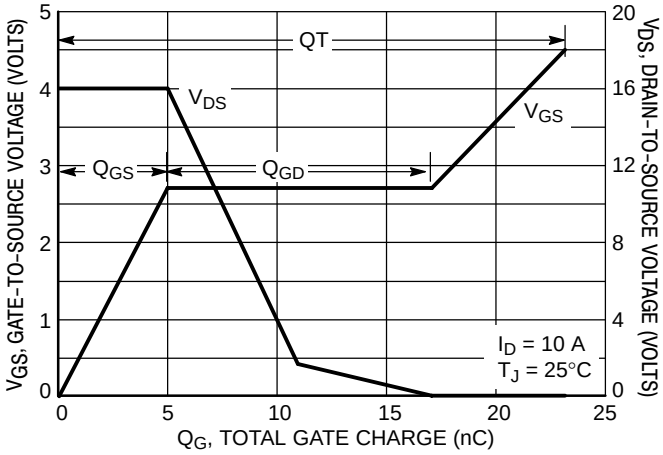


Figure 8. Gate−To−Source and Drain−To−Source Voltage vs. Total Charge

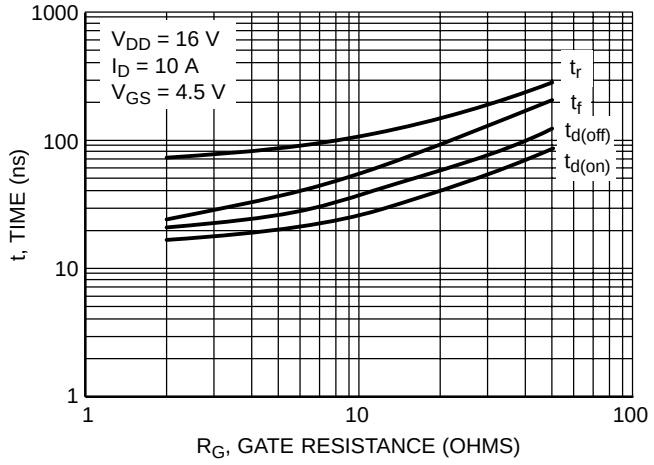


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

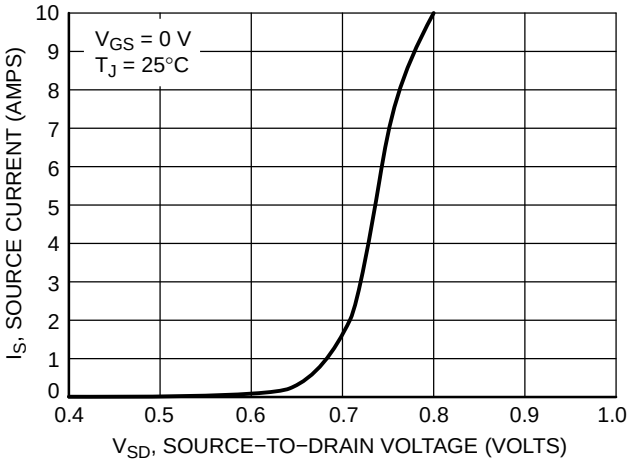
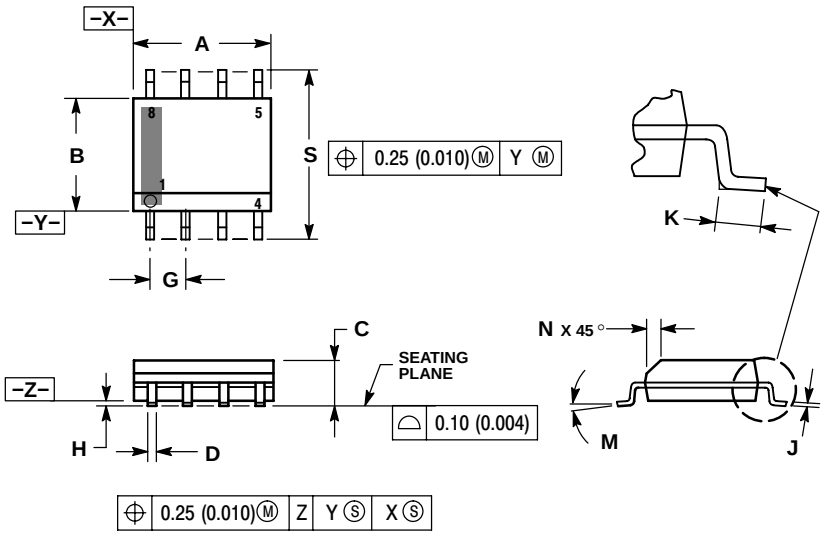


Figure 10. Diode Forward Voltage vs. Current

PACKAGE DIMENSIONS

SOIC−8 NB
CASE 751−07
ISSUE AH

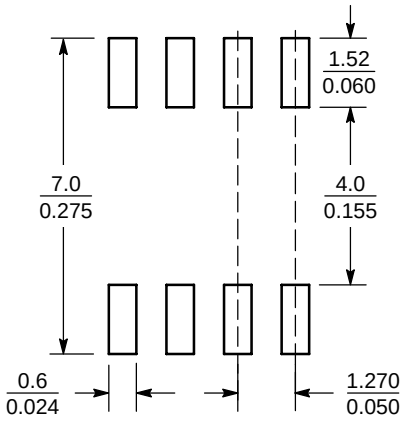


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751−01 THRU 751−06 ARE OBSOLETE. NEW STANDARD IS 751−07.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

STYLE 12:
PIN 1. SOURCE
2. SOURCE
3. SOURCE
4. GATE
5. DRAIN
6. DRAIN
7. DRAIN
8. DRAIN

SOLDERING FOOTPRINT*



SCALE 6:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
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